

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitance load, derate current by 20%.

Characteristic	Symbol	B320	B330	B340	B350	B360	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	20	30	40	50	60	V
Working Peak Reverse Voltage	V_{RWM}						
DC Blocking Voltage	V_R						
Average Rectified Output Current	I_O	3.0					A
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	100					A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal	$R_{\theta JT}$	20	$^\circ\text{C/W}$
Typical Thermal Resistance, Junction to Ambient (Note 7)	$R_{\theta JA}$	90	$^\circ\text{C/W}$
Operating Temperature Range	T_J	-55 to +150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V_F	—	—	0.50 0.70	V	$I_F = 3.0\text{A}$, $T_A = +25^\circ\text{C}$ B320, B330, B340 B350, B360
Leakage Current (Note 8)	I_R	—	—	0.5 20	mA	@ Rated V_R , $T_A = +25^\circ\text{C}$ @ Rated V_R , $T_A = +100^\circ\text{C}$
Total Capacitance	C_T	—	—	200	pF	$V_R = 4\text{V}$, $f = 1\text{MHz}$

Notes: 7. Thermal Resistance: Junction to terminal, unit mounted on glass epoxy substrate with 2x3mm copper pad
 8. Short duration pulse test used to minimize self-heating effect.

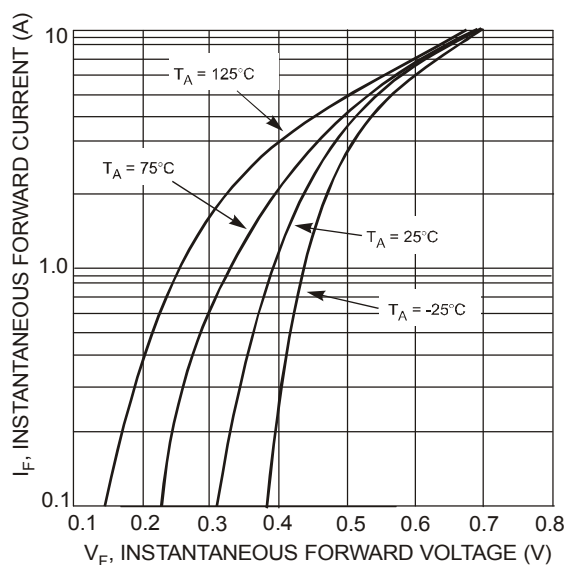


Fig. 1 Typical Forward Characteristics - B320B thru B340B

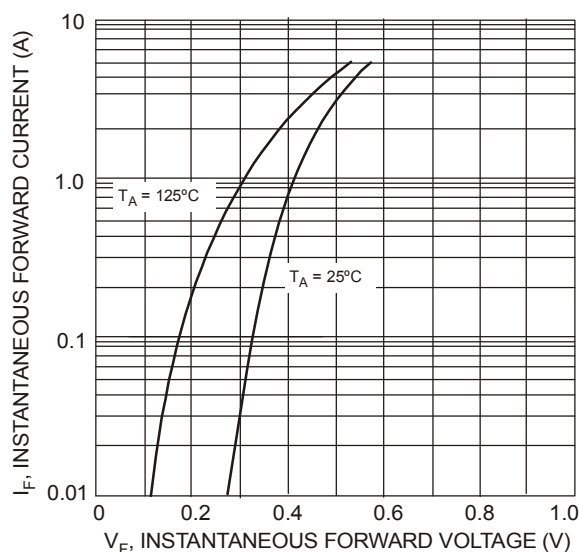


Fig. 2 Typical Forward Characteristics - B350B thru B360B

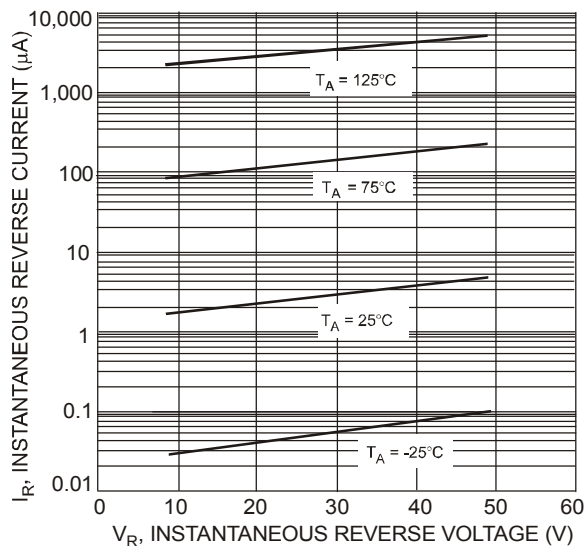


Fig. 3 Typical Reverse Characteristics, B320B thru B340B

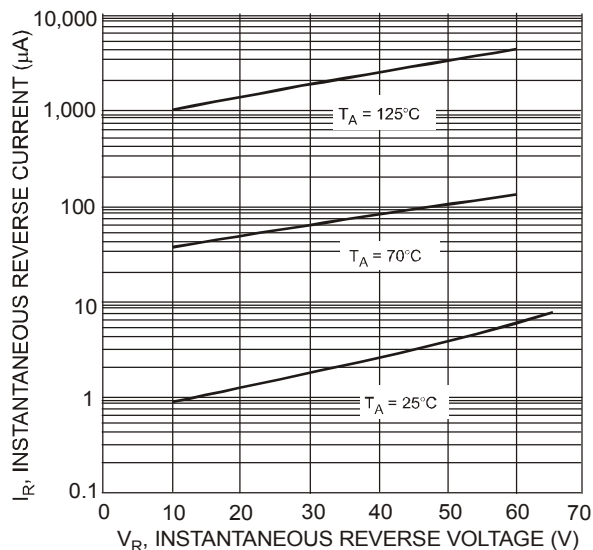


Fig. 4 Typical Reverse Characteristics, B350B thru B360B

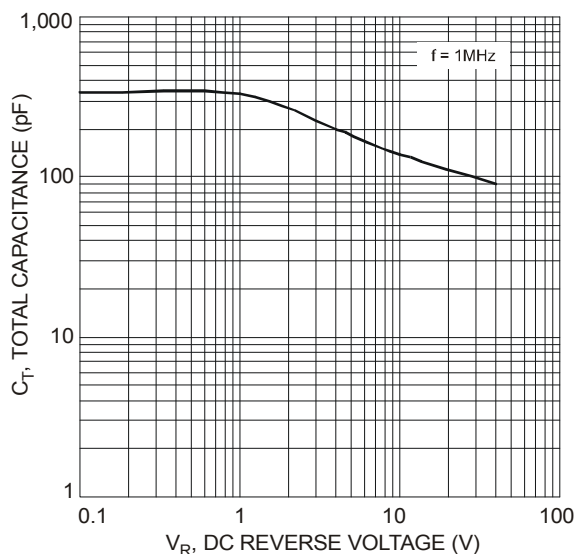


Fig. 5 Total Capacitance vs. Reverse Voltage

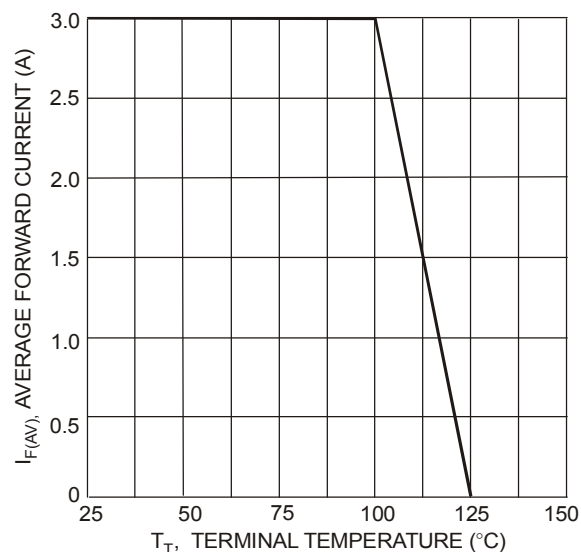


Fig. 6 Forward Current Derating Curve

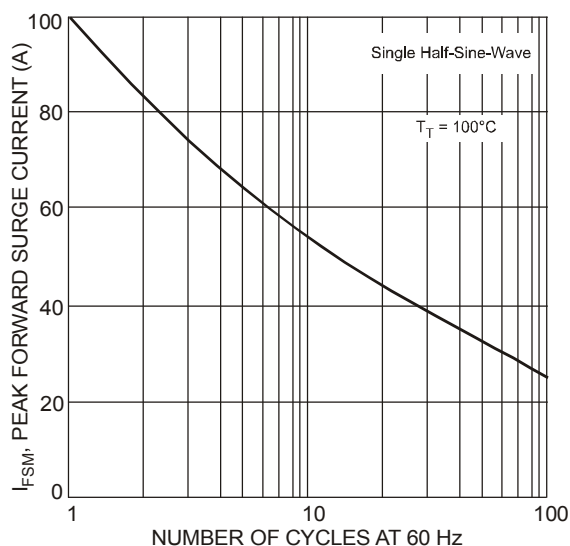
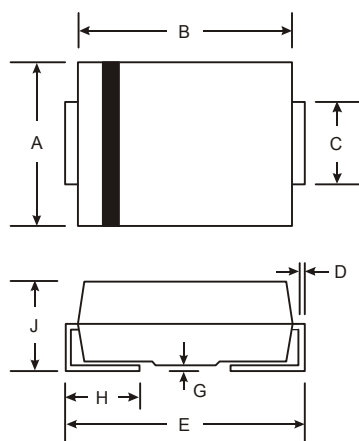


Fig. 7 Max Non-Repetitive Peak Forward Surge Current

Package Outline Dimensions

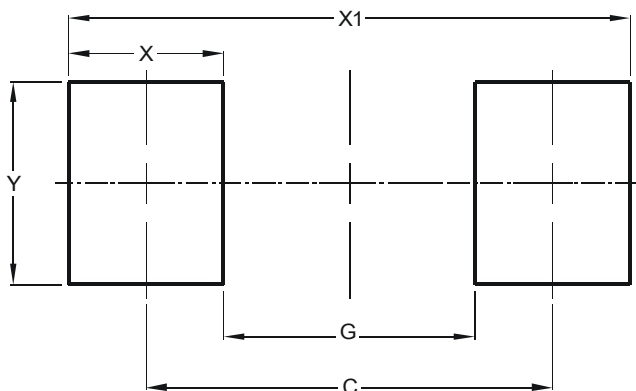
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SMC		
Dim	Min	Max
A	5.59	6.22
B	6.60	7.11
C	2.75	3.18
D	0.15	0.31
E	7.75	8.13
G	0.10	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	6.80
G	4.40
X	2.50
X1	9.40
Y	3.30

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